

NC7SZ384

TinyLogic™ UHS 1-Bit Low Power Bus Switch

General Description

The NC7SZ384 provides 1-bit of ultra high-speed CMOS TTL-compatible bus switch. The low On Resistance of the switch allows inputs to be connected to outputs with minimal propagation delay and without generating additional ground bounce noise. The device is organized as a 1-bit switch with a bus enable (\overline{OE}) signal. When \overline{OE} is LOW, the switch is on and Port A is connected to Port B. When \overline{OE} is HIGH, the switch is open and a high-impedance state exists between the two ports.

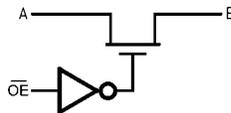
Features

- Space saving SOT23 or SC70 5-lead package
- Ultra small MicroPak™ leadless package
- 5Ω switch connection between two ports
- Minimal propagation delay through the switch
- Low I_{CC}
- Zero bounce in flow-through mode
- Control inputs compatible with TTL level

Ordering Code:

Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7SZ384M5X	MA05B	8Z84	5-Lead SOT23, JEDEC MO-178, 1.6mm	3k Units on Tape and Reel
NC7SZ384P5X	MAA05A	Z84	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3k Units on Tape and Reel
NC7SZ384L6X	MAC06A	C3	6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel

Logic Diagram



Pin Description

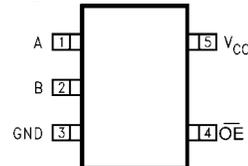
Pin Name	Description
\overline{OE}	Bus Switch Enable
A	Bus A
B	Bus B
NC	No Connect

Truth Table

\overline{OE}	B_O A_O	Function
L		Connect
H		HIGH-Z State

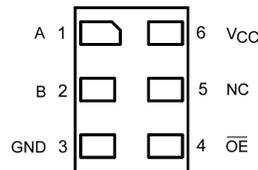
Connection Diagrams

Pin Assignments for SOT23 and SC70



(Top View)

Pad Assignments for MicroPak



(Top Thru View)

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Absolute Maximum Ratings (Note 1)		Recommended Operating Conditions (Note 3)	
Supply Voltage (V_{CC})	-0.5V to +7.0V	Power Supply Operating (V_{CC})	4.0V to 5.5V
DC Switch Voltage (V_S)	-0.5V to +7.0V	Input Voltage (V_{IN})	0V to 5.5V
DC Input Voltage (V_{IN}) (Note 2)	-0.5V to +7.0V	Output Voltage (V_{OUT})	0V to 5.5V
DC Input Diode Current (I_{IK}) $V_{IN} < 0V$	-50 mA	Input Rise and Fall Time (t_r, t_f)	
DC Output (I_{OUT}) Sink Current	128 mA	Switch Control Input	0 ns/V to 5 ns
DC V_{CC}/GND Current (I_{CC}/I_{GND})	± 100 mA	Switch I/O	0 ns/V to DC
Storage Temperature Range (T_{STG})	-65°C to +150°C	Operating Temperature (T_A)	-40°C to +85°C
Junction Temperature under Bias (T_J)	+150°C	Thermal Resistance (θ_{JA})	
Junction Lead Temperature (T_L) (Soldering, 10 Seconds)	+260°C	SOT23-5	300°C/W
Power Dissipation (P_D) @ +85°C		SC70-5	425°C/W
SOT23-5	200 mW	Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.	
SC70-5	150 mW	Note 2: The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.	
		Note 3: Unused inputs must be held HIGH or LOW. They may not float.	

DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	$T_A = -40^\circ\text{C to } +85^\circ\text{C}$			Units	Conditions
			Min	Typ	Max		
V_{IK}	Clamp Diode Voltage	4.5			-1.2	-V	$I_{IN} = -18$ mA
V_{IH}	HIGH Level Input Voltage	4.5-5.5	2.0			V	
V_{IL}	LOW Level Input Voltage	4.5-5.5			0.8	V	
I_{IN}	Input Leakage Current	5.5			± 1.0	μA	$0 \leq V_{IN} \leq 5.5V$
I_{OFF}	"OFF" Leakage Current	5.5			± 10.0	μA	$0 \leq A, B \leq V_{CC}$
R_{ON}	Switch On Resistance (Note 4)	4.5		3	7	Ω	$V_{IN} = 0V, I_{IN} = 64$ mA
		4.5		3	7	Ω	$V_{IN} = 0V, I_{IN} = 30$ mA
		4.5		6	15	Ω	$V_{IN} = 2.4V, I_{IN} = 15$ mA
		4.0		10	20	Ω	$V_{IN} = 2.4V, I_{IN} = 15$ mA
I_{CC}	Quiescent Supply Current	5.5			10	μA	$V_{IN} = V_{CC}$ or GND $I_O = 0$
ΔI_{CC}	Increase in I_{CC} per Input (Note 5)	5.5		0.9	2.5	mA	$V_{IN} = 3.4V, I_O = 0$, Control Input only

Note 4: Measured by the voltage drop between A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the two (A or B) pins.

Note 5: Per TTL driven input ($V_{IN} = 3.4V$, control input only). A and B pins do not contribute to I_{CC} .

AC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	T _A = -40°C to +85°C, C _L = 50 pF, R _U = R _D = 500Ω			Units	Conditions	Figure Number
			Min	Typ (Note 6)	Max			
t _{PHL} t _{PLH}	Prop Delay Bus to Bus (Note 7)	4.0-5.5			0.25	ns	V _I = OPEN	Figures 1, 2
t _{PZL} t _{PZH}	Output Enable Time	4.5-5.5	1.0	2.5	5.0	ns	V _I = 7V for t _{PZL} V _I = OPEN for t _{PZH}	Figures 1, 2
t _{PLZ} t _{PHZ}	Output Disable Time	4.5-5.5	1.0	2.5	5.0	ns	V _I = 7V for t _{PLZ} V _I = OPEN for t _{PHZ}	Figures 1, 2
		4.0	1.0		5.5	ns		

Capacitance (Note 8)

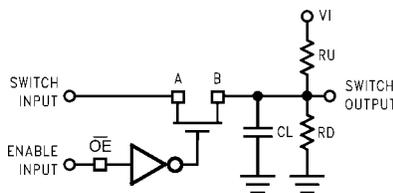
Symbol	Parameter	Typ	Max	Units	Conditions
C _{IN}	Control Pin Input Capacitance	2	6	pF	V _{CC} = 5.0V
C _{I/O}	Input/Output Capacitance	4.5	10	pF	V _{CC} , \overline{BE} = 5.0V

Note 6: All typical values are V_{CC} = 5.0V, T_A = 25°C.

Note 7: This parameter is guaranteed by design but is not tested. The bus switch contributes no propagation delay other than the RC delay of the typical On resistance of the switch and the 50 pF load capacitance, when driven by an ideal voltage source (zero output impedance).

Note 8: T_A = 25°C, f = 1 MHz.

AC Loading and Waveforms



Input driven by 50Ω source terminated in 50Ω

C_L includes load and stray capacitance

Input PRR = 1.0 MHz; t_W = 500 ns

FIGURE 1. AC Test Circuit

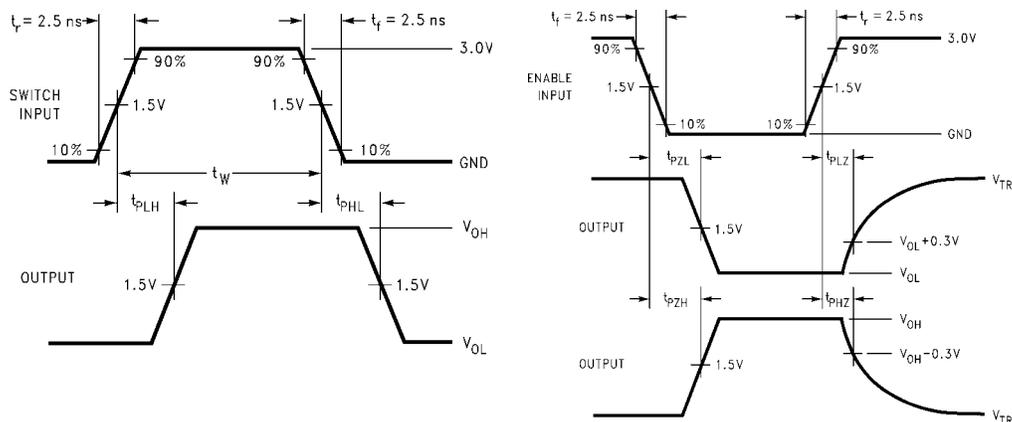


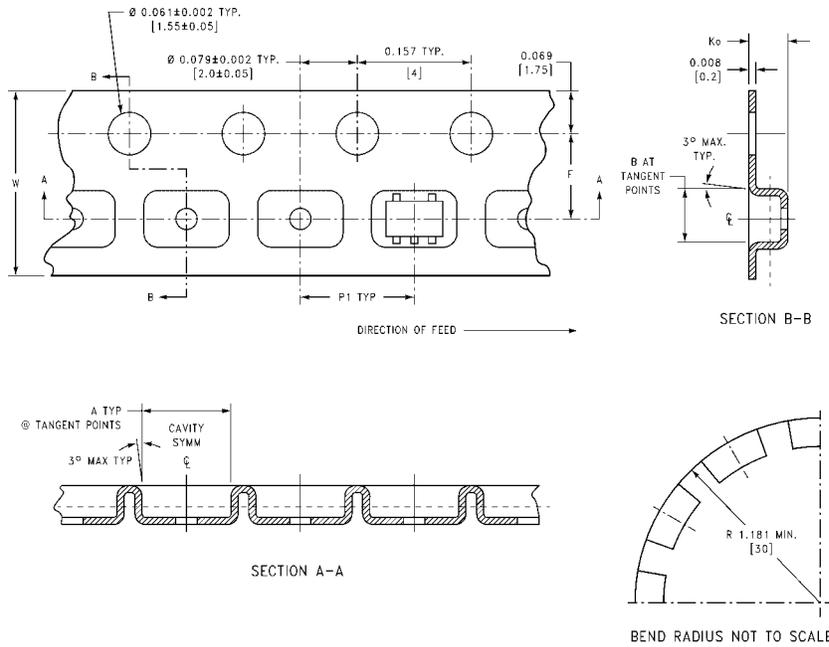
FIGURE 2. AC Waveforms

Tape and Reel Specification

TAPE FORMAT for SOT23 and SC70

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
M5X, P5X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

TAPE DIMENSIONS inches (millimeters)

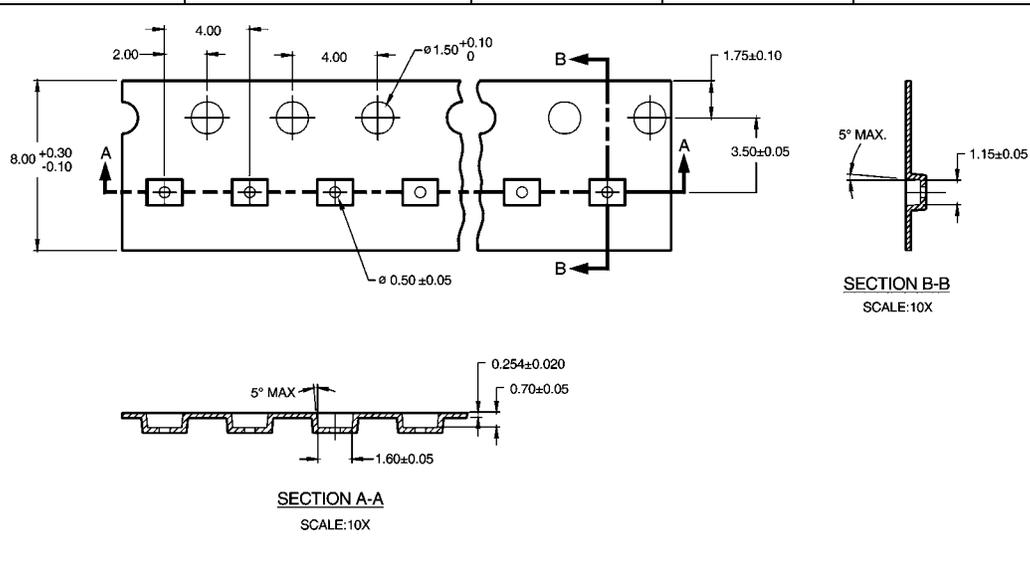


Package	Tape Size	DIM A	DIM B	DIM F	DIM K ₀	DIM P1	DIM W
SC70-5	8 mm	0.093 (2.35)	0.096 (2.45)	0.138 ± 0.004 (3.5 ± 0.10)	0.053 ± 0.004 (1.35 ± 0.10)	0.157 (4)	0.315 ± 0.004 (8 ± 0.1)
SOT23-5	8 mm	0.130 (3.3)	0.130 (3.3)	0.138 ± 0.002 (3.5 ± 0.05)	0.055 ± 0.004 (1.4 ± 0.11)	0.157 (4)	0.315 ± 0.012 (8 ± 0.3)

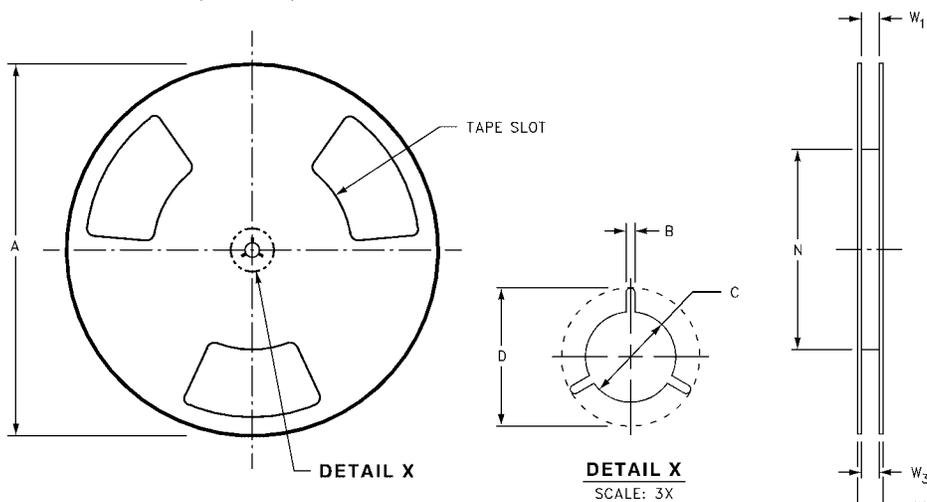
Tape and Reel Specification (Continued)

TAPE FORMAT for MicroPak

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
L6X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

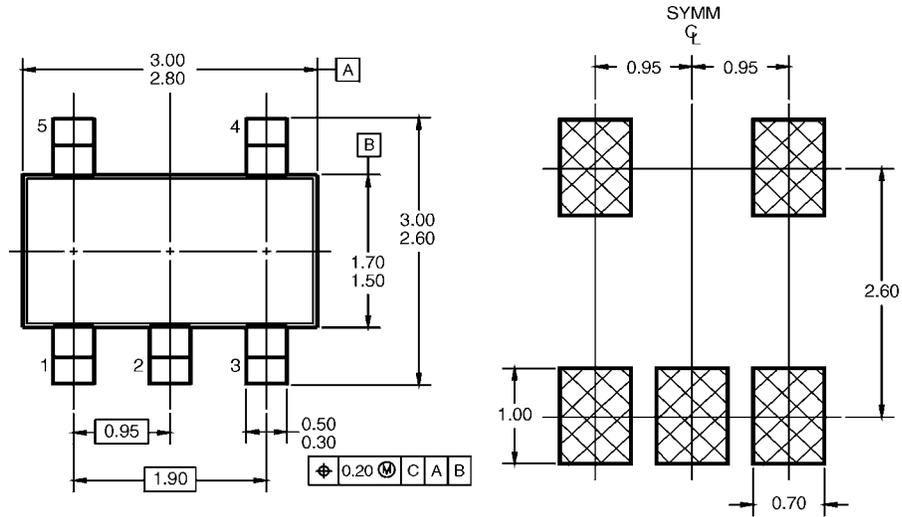


REEL DIMENSIONS inches (millimeters)

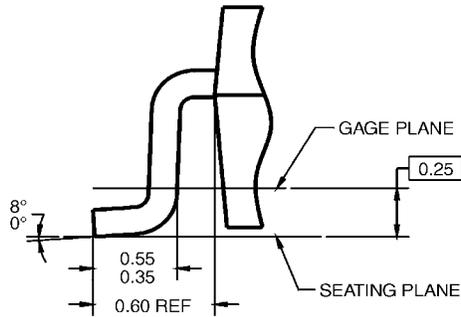
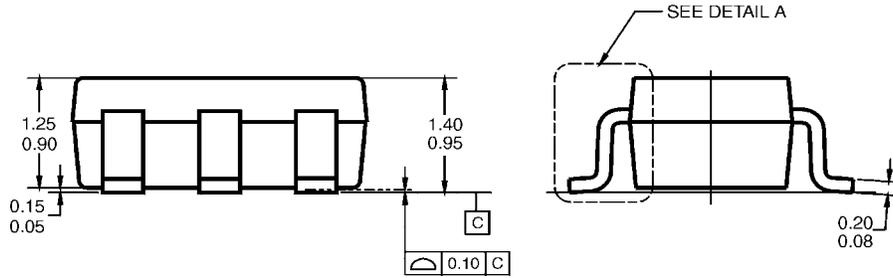


Tape Size	A	B	C	D	N	W1	W2	W3
8 mm	7.0 (177.8)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.331 + 0.059/-0.000 (8.40 + 1.50/-0.00)	0.567 (14.40)	W1 + 0.078/-0.039 (W1 + 2.00/-1.00)

Physical Dimensions inches (millimeters) unless otherwise noted



LAND PATTERN RECOMMENDATION



DETAIL A

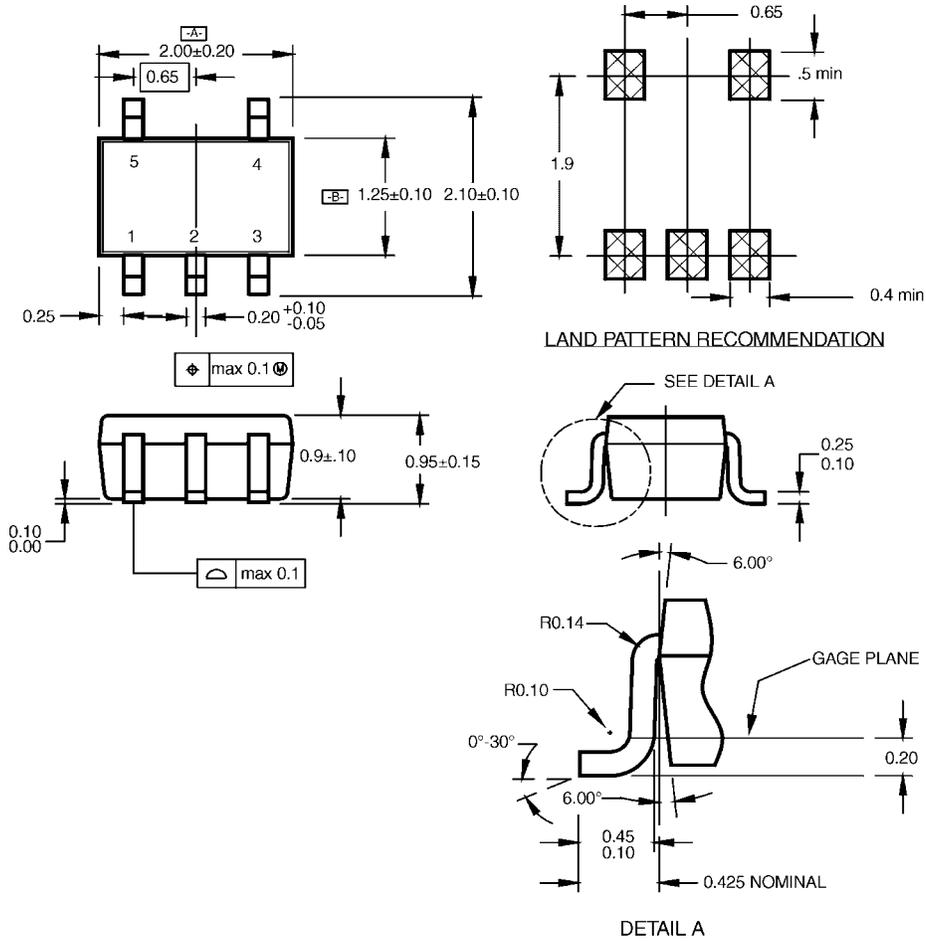
NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MO-178, ISSUE B, VARIATION AA, DATED JANUARY 1999.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.

MA05BRevC

5-Lead SOT23, JEDEC MO-178, 1.6mm
Package Number MA05B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



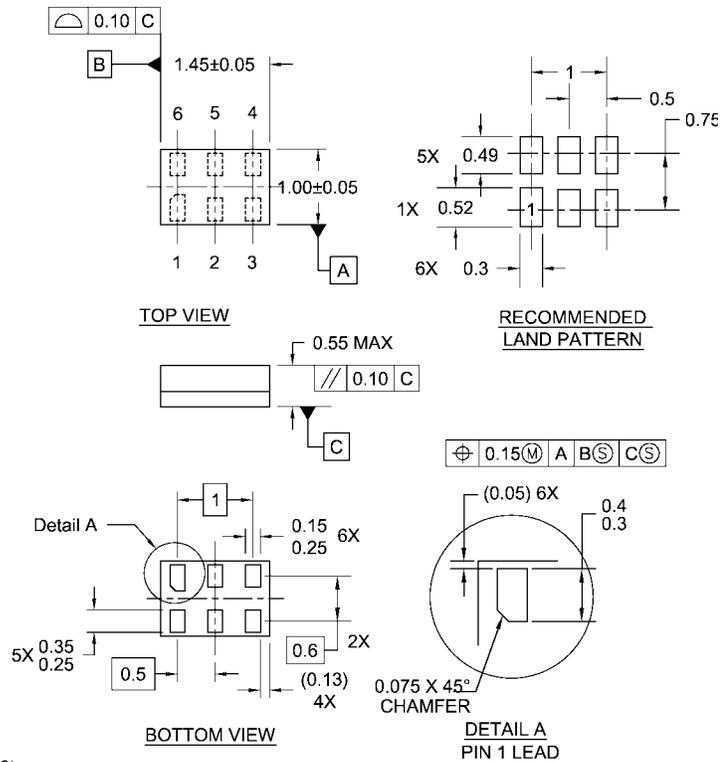
NOTES:

- A. CONFORMS TO EIAJ REGISTERED OUTLINE DRAWING SC88A.
- B. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.
- C. DIMENSIONS ARE IN MILLIMETERS.

MAA05ARevC

**5-Lead SC70, EIAJ SC-88a, 1.25mm Wide
Package Number MAA05A**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Notes:

1. JEDEC PACKAGE REGISTRATION IS ANTICIPATED
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06ARevB

**6-Lead MicroPak, 1.0mm Wide
Package Number MAC06A**

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